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NEMI's Lead Free Transition Task Group

Project: Component and Board Marking Working Group

Statement of Work

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Purpose:

The group intends to develop proposals to resolve the issues leading to an industry accepted Pb-free component and board-marking standard by February 2004 (Primary Goal).

The group also intends to develop project requirements, to resolve the issues leading to an industry accepted RoHS compliant component and board-marking standard by mid-2004 (Secondary Goal), a part numbering guideline and a vocabulary for use during the transition to RoHS .

Background:

One of the issues surrounding the transition of electronics industry to Pb-free assembly (RoHS compliant products) is the marking of components, boards and end products. There are several Pb-free marking schemes being used in the industry, and with the proliferation of Pb-free manufacturing, so are the number of schemes. JEDEC has had a marking proposal on the ballot since June, 2003 which has received multiple inputs, but has not yet been approved. The IPC Blue Ribbon group is reviewing the JEDEC specification, and SolderTech-UK has sent out a labeling survey. There are several marking schemes in use by individual companies, but there are no other known standard activities.

Scope of Work:

1. Develop a recommendation for a standard for the labeling and marking of Pb-free components, cards and motherboards; both in raw material and finished product form.
2. Recommendation for part numbering best known practices
3. Create recommendation in line with steps 1 & 2 for RoHS compliant standard.
4. Create a recommended vocabulary to address different stages of transition to RoHS

Discussion Topics:

Lead-free part identification – unique part number, symbols, and identifiers?
Establish a common industry standard
Actual part numbering schemes – except those covered in the first scope statement.
Identify gaps from the existing JEDEC specification
Use of a common scheme (nomenclature) for both boards and components

Parking Lot Items:

Point of sale and retail box marking is excluded
Halogen-free marking or identification

Team Milestones – Schedule/ Status:

• Collect current list of marking schemes	December, 2003	Done
• Define a minimum set of requirements to be addressed by standard	January, 2004	
Done		
• Develop a recommendation for closing gap(s) in standards	January, 2004	Done
• Calibrate with other NEMI sub-teams and industry efforts	February, 2004	Done
• Get NEMI Lead-Free Transition Task Group approval of standard	February, 2004	
March		
• Publicize the standard with IPC, JEDEC, HDPUG, etc.	March, 2004	April
• Publication of Electronics Part Identification Standard(s)	May, 2004	
• Publication of Pb-free vocabulary	May 2004	

Specifications and Standards:

TBD

Roles and Responsibilities:

TBD

Glossary of Terms:

TBD